
IN THE CLAIMS:

3. (CURRENTLY AMENDED) A semiconductor device, comprising:
a conductive layer pattern formed on a substrate;
~~an~~ a first inter-layer insulating film which covers said conductive layer pattern and is formed on said substrate;
a first connection hole formed in an upper layer of said first inter-layer insulating film above said conductive layer pattern;
a second connection hole which reaches said conductive layer pattern from the bottom portion of said first connection hole and then has a smaller diameter than that of said first connection hole and formed on said first inter-layer insulation film;
a plug having conductivity and ~~formed in a state~~ filling internal portions of said first connection hole and said second connection hole;
~~an upper~~ a second inter-layer insulating film formed on said first inter-layer insulating film, wherein said second inter-layer insulating film includes up to five layers;
a third connection hole which reaches said plug and is formed ~~on~~ through said second inter-layer insulating film; and
a conductive portion which is connected to said plug and formed in said third connection hole.

4. (CURRENTLY AMENDED) A semiconductor device, comprising:
a conductive layer pattern formed on a substrate;
~~an~~ a first inter-layer insulating film which covers said conductive layer pattern and is formed on said substrate;
a first connection hole formed in an upper layer of said first inter-layer insulating film above said conductive layer pattern;
a second connection hole which reaches said conductive layer pattern from the bottom portion of said first connection hole and then has a smaller diameter than that of said first connection hole and formed on said first inter-layer insulation film;
a plug having conductivity and ~~formed in a state~~ filling internal portions of said first connection hole and said second connection hole, wherein the upper surface of said plug is

formed to almost the same height as the surface height of said first inter-layer insulating film;
~~an upper~~ a second inter-layer insulating film formed on said first inter-layer
insulating film, wherein said second inter-layer insulating film includes up to five layers;
a third connection hole which reaches said plug and is formed ~~on~~ through said
second inter-layer insulating film; and
a conductive contact portion which is connected to said plug and formed in said
third connection hole.

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5. (ORIGINAL) A semiconductor device according to claim 3, wherein said
plug and said conductive portion are a storage node contact portion of a dynamic random access
memory.

6. (ORIGINAL) A semiconductor device according to claim 4, wherein said
plug and said conductive portion are a storage node contact portion of a dynamic random access
memory.
